Vishay Vitramon MLCC End Termination

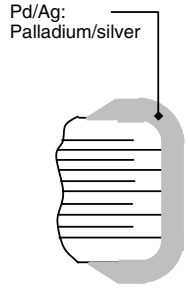

Figure 1:
Termination codes: F, M,

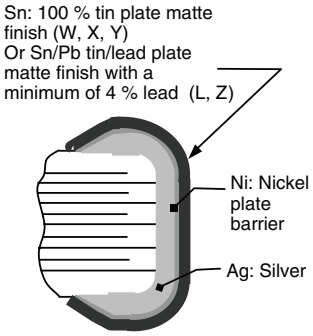

Figure 2:
Termination codes: L, W, X, Y, Z

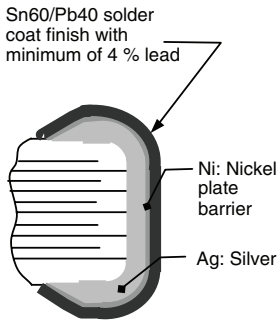

Figure 3:
CDR Termination code: U

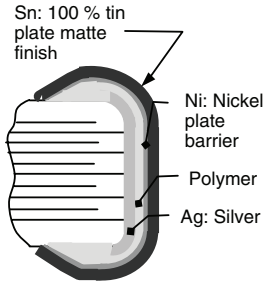

Figure 4:
Termination code: B

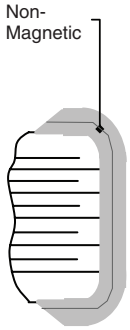

Figure 5:
Termination code: N

TERMINATION CODE	TERMINATION DEFINITION	RECOMMENDED SOLDER APPLICATION
F, M [3]	Fired, thick film, silver/palladium	Conductive epoxy/Reflow solder/ wave solder [1] [2]
N	Fired, thick film, non magnetic material	Conductive epoxy/Reflow solder
W [3], X, Y [3]	Fired, thick film silver, covered by 100 % nickel barrier plate with an outer layer of 100 % tin plate matte finish for multi-solder mounting	Wave solder [1]/reflow solder/ vapor phase reflow
L, Z [3]	Fired, thick film silver, cover by 100 % nickel barrier plate with an outer layer of tin/lead plate matte finish with a minimum of 4 % lead for multi-solder mounting	Wave solder [1]/reflow solder/ vapor phase reflow
U [4]	Fired, thick film silver, cover by 100 % nickel barrier plate with an outer layer of tin/lead plate finish matte with a minimum of 4 % lead for Sn60/Pb40 solder coat	Wave solder [1]/reflow solder/ vapor phase reflow
B	Fired, thick film silver, cured thick film polymer silver, covered by 100 % nickel barrier plate with an outer layer of 100 % tin plate matte finish for multi-solder mounting	Wave solder [1]/reflow solder/ vapor phase reflow

Notes:

[1] Case sizes 1210 to 1812 with a thickness > 0.049" (1.24 mm) and case sizes 1825 and larger should NOT be wave solder.

[2] Recommend only one wave soldering pass of silver/palladium termination for non-plated terminations (F, M and N).Parts cannot be rework.

[3] CDR and DSCC part numbers only.

[4] CDR "U" termination code: Base metallization-barrier metal-solder coated (tin/lead alloy, with a minimum of 4 % lead). Solder has a melting point of + 200 °C or less. Solder coat thickness is a minimum of 60 inches.

- Solder iron techniques are not recommended. For more information on soldering visit www.vishay.com/doc?45034
- Contact mlcc.specials@vishay.com with respect to specific part number requirements.

Vishay Vitramon MLCC End Termination

MLCC END TERMINATION PHYSICAL CHARACTERISTICS							
P/N TERM CODE	THICK FILM END TERMINATION		BARRIER TERMINATION	TERMINATION FINISH			
	MATERIAL	THICKNESS (inches)	Ni PLATE THICKNESS (microinches)	Sn PLATE THICKNESS (microinches)	Sn/Pb PLATE THICKNESS (microinches)	Sn/Pb SOLDER COAT THICKNESS (microinches)	CONTENT OF LEAD
F, M	Ag/Pd	0.001 min.	N/a	N/a	N/a	N/a	N/a
N	Ag/Pd	0.0012 min.	N/a	N/a	N/a	N/a	N/a
W, X, Y	Ag	0.001 min.	50 min.	100 min.	N/a	N/a	N/a
L, Z	Ag	0.001 min.	50 min.	N/a	100 min.	N/a	4 % min.
U	Ag	0.001 min.	50 min.	N/a	N/a	60 min.	4 % min.
B	Polymer	0.003 min.	50 min.	100 min.	N/a	N/a	N/a

Element Definition: Ag = Silver, Pd = Palladium, Ni = Nickel, Sn = Tin, Pb = Lead